IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	Material Compo © Copyright 2005. IF international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier Info	rmation														
Company name*		Company unique ID			τ	Unique ID Authority					Response Date*				
onsemi											2024-05	2024-05-03			
Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Ste	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product E				luct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	Mfr Item Number		Mfr Item Name			Effective Dat	te Vers	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		A5191HRTLG-XTP A5191HRTLG		A5191HRTLG HA	HART MODEM ASS		2024-05-03			PHG		170.69	mg	Each	
Ianufacturin	g Proccess Informat	tion													
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperat		re Max Time at Peal	k Tempera	ture Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 3			260 C 30		30	seconds 3						
omments															
<b>TTENTION:</b> M	ISL 3 Rated item requires	Bake and D	ry Pack (after	r electrical test)											
or more informa	ation regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material Weight		Unit of Measure Level		Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.79	mg	Supplier	Silicon (Si)	7440-21-3		13.79	mg
Die Attach	3.03	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.6666	mg
			Supplier	Silver (Ag)	7440-22-4		2.3634	mg
Lead Frame	56.68	mg	Supplier	Tin (Sn)	7440-31-5		0.1417	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1134	mg
			Supplier	Chromium (Cr)	7440-47-3		0.17	mg
			Supplier	Copper (Cu)	7440-50-8		56.2549	mg
Mold Compound-Black	93.68	mg		Epoxy Phenol Resin	proprietary data		11.2416	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		82.4384	mg
Plating	2.64	mg	Supplier	Tin (Sn)	7440-31-5		2.64	mg
Wire Bond - Au	0.87	mg	Supplier	Gold (Au)	7440-57-5		0.87	mg